

# 18-Channel Intelligent RGB LED Driver

## Features

- 18-channel RGB LED Driver
- Independent color mixing register per channel
- Maximum output current: 25.5mA
- High-precision current sinks
  - Device to device error:  $\pm 7\%$
  - Channel to channel error:  $\pm 7\%$
- Power save mode when all LED off > 30ms
- 400kHz I<sup>2</sup>C interface, 4 independent addresses, 1 broadcast address
- Power supply: 2.7V to 5.5V
- QFN 4mm x 4mm x 0.85mm 32L package

## Applications

- Smart speaker
- E-sports devices
- Smart home appliances

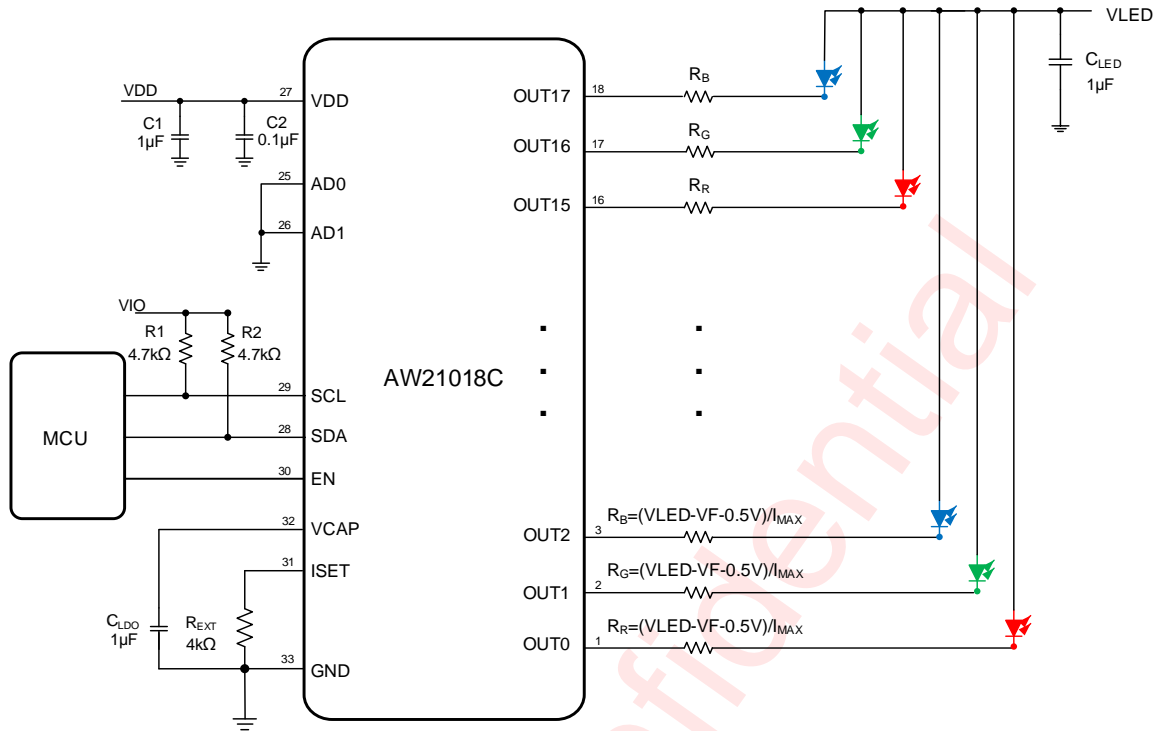
## General Description

AW21018C is a 18-channel high precision constant current LED driver. The maximum current of each channel is recommended to be configured via external resistor  $R_{EXT}$ .

AW21018C can be turned off with minimum current consumption by pulling the EN pin low. When EN pin pull high and all LEDs off >30ms, AW21018C enters power save mode.

AW21018C is available in QFN 4mm x 4mm x 0.85mm-32L package. It operates from 2.7V to 5.5V over the temperature range of  $-40^{\circ}\text{C}$  to  $105^{\circ}\text{C}$ .

### Typical Application Circuit



Note: The resistors( $R_R$ ,  $R_G$ ,  $R_B$ ) between LED and IC are only for thermal reduction. For more information, please refer to application information.

Figure 1 Application Circuit

### Pin Configuration And Top Mark

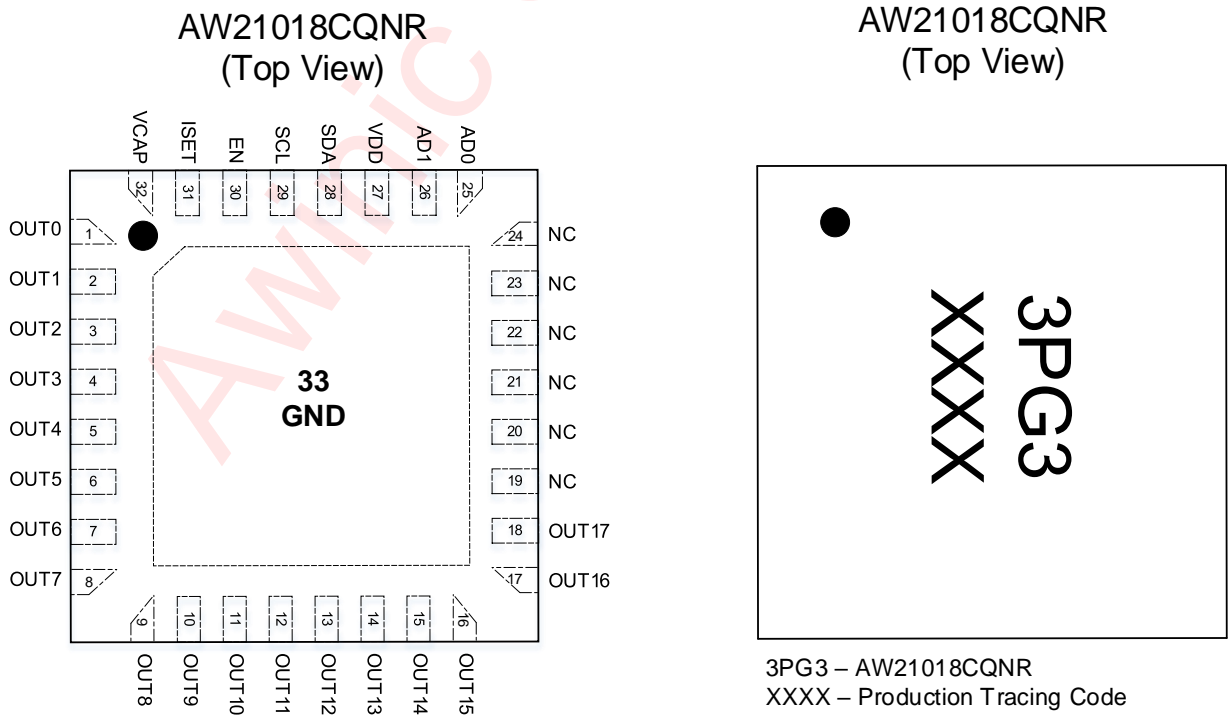


Figure 2 Pin Configuration and Marking

## Pin Definition

| No.   | NAME       | DESCRIPTION   |
|-------|------------|---|
| 1~18  | OUT0~OUT17 | Constant current sink, connect to LED's cathode   |
| 25~26 | AD0, AD1   | I <sup>2</sup> C address setting, connects to GND or VDD for different device address of I <sup>2</sup> C |
| 27    | VDD        | Power supply  |
| 28    | SDA        | Serial data I/O for I <sup>2</sup> C interface  |
| 29    | SCL        | Serial clock input for I <sup>2</sup> C interface   |
| 30    | EN         | Shutdown the chip when pulled low.  |
| 31    | ISET       | Input terminal used to connect an external resistor. This regulates the global output current             |
| 32    | VCAP       | Connect a 1 $\mu$ F capacitor to GND.   |
| 33    | GND        | Ground  |

## Functional Block Diagram

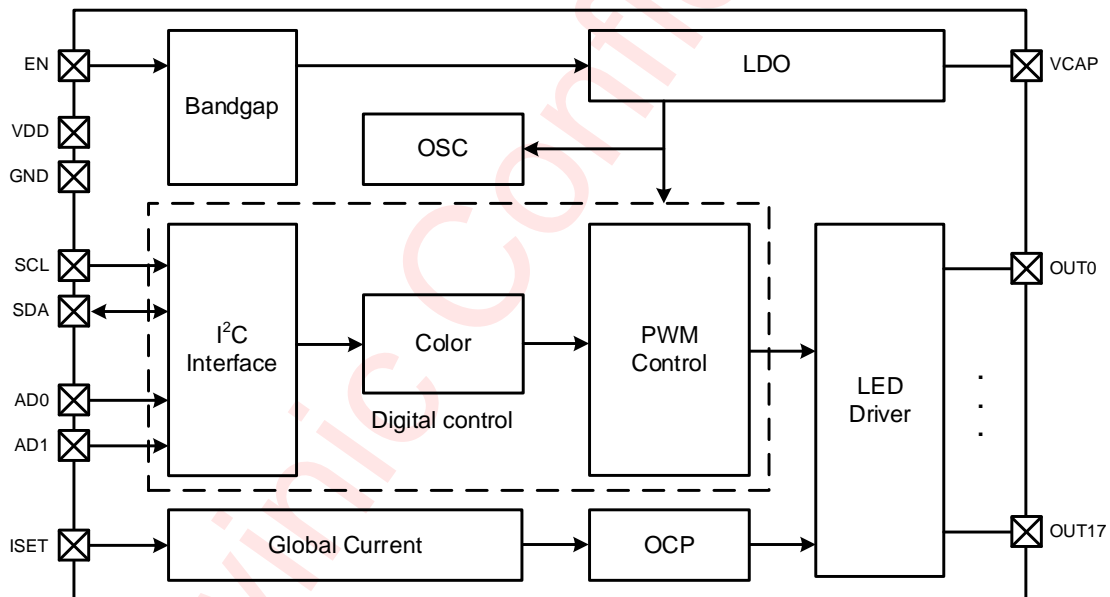


Figure 3 Functional Block Diagram

## Ordering Information

| Part Number | Temperature | Package     | Marking | Moisture Sensitivity Level | Environmental Information | Delivery Form                |
|-------------|-------------|-------------|---------|----------------------------|---------------------------|------------------------------|
| AW21018CQNR | -40°C~105°C | QFN 4X4-32L | 3PG3    | MSL3                       | ROHS+HF                   | 3000 units/<br>Tape and Reel |

## Absolute Maximum Ratings<sup>(NOTE1)</sup>

Over operating ambient temperature range (unless otherwise noted)<sup>(1)</sup>

| PARAMETERS   |                   | RANGE                     |
|--|-------------------|---------------------------|
| Supply voltage range $V_{DD}$                        |                   | -0.3V to 6V               |
| Input voltage range                                  | EN, ADx, SCL, SDA | -0.3V to 6V               |
| Output voltage range                                 | OUTx, ISET        | -0.3V to 6V               |
|  | VCAP              | -0.3V to 2.5V             |
| Junction-to-ambient thermal resistance $\theta_{JA}$ |                   | 36.4°C/W                  |
| Maximum operating junction temperature $T_{J-MAX}$   |                   | 150°C                     |
| Storage temperature, $T_{stg}$                       |                   | -65°C to 150°C            |
| ESD (NOTE 2)   |                   |                           |
| HBM  |                   | ±2kV                      |
| CDM  |                   | ±1.5kV                    |
| Latch-Up   |                   |                           |
| Test condition: JESD78F                              |                   | +IT: 200mA<br>-IT: -200mA |

**NOTE1:** Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should be within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

**NOTE2:** The human body model is a 100pF capacitor discharged through a 1.5kΩ resistor into each pin. HBM test method: ESDA/JEDEC JS-001-2023, CDM test method: ESDA/JEDEC JS-002-2022.

## Recommended Operating Conditions

Over operating ambient temperature range (unless otherwise noted)

| Symbol         | Parameter                            | MIN | TYP | MAX | UNIT |
|----------------|--------------------------------------|-----|-----|-----|------|
| $V_{DD}$       | Supply voltage                       | 2.7 |     | 5.5 | V    |
| $V_{PULL-UP}$  | SCL/SDA pull-up voltage              | 1.7 |     | 5.5 | V    |
| $C_1, C_{LED}$ | Input capacitance                    | 1   |     |     | μF   |
| $C_2$          | Input capacitance                    | 0.1 |     |     | μF   |
| $C_{LDO}$      | Internal LDO capacitance             | 1   |     |     | μF   |
| $R_{EXT}$      | Output current setting resistance    | 2   |     |     | kΩ   |
| $T_A$          | Operating free-air temperature range | -40 | 25  | 105 | °C   |

## Electrical Characteristics

T<sub>A</sub>=25°C, V<sub>DD</sub>=3.6V (unless otherwise noted)

| PARAMETER                               |  | TEST CONDITION   | MIN | TYP  | MAX  | UNIT |
|---|--|--|-----|------|------|------|
| <b>Power supply voltage and current</b> |  |  |     |      |      |      |
| V <sub>DD</sub>                         | Supply voltage   |  | 2.7 |      | 5.5  | V    |
| I <sub>SD</sub>                         | Shutdown supply current  | V <sub>EN</sub> =0   |     | 0.1  | 2    | μA   |
| I <sub>STB</sub>                        | Standby supply current   | V <sub>EN</sub> =3.3V, CHIPEN=0  |     | 6    | 20   |      |
| I <sub>PS</sub>                         | Power-save mode supply current <sup>NOTE(1)</sup>  | V <sub>EN</sub> =3.3V,CHIPEN=0,POWER_SAVE_EN=1,all the LEDs off duration > 30ms(typical) |     | 6    | 20   |      |
| I <sub>ACT</sub>                        | Normal-mode supply current   | I <sub>OUTX</sub> =10mA, PWM=100%  |     | 1.5  | 6    | mA   |
| I <sub>MAX</sub>                        | Maximum output current   | V <sub>OUTX</sub> =1V, PWM=100%  |     |      | 25.5 | mA   |
| I <sub>LIM</sub>                        | Internal output current limit  | V <sub>OUTX</sub> =1V, PWM=100%  | 35  | 50   |      |      |
| I <sub>lkg</sub>                        | Leakage current  | PWM=0  |     | 0.1  | 1    | μA   |
| I <sub>accuracy</sub>                   | Device to device current error, I <sub>ERR_DD</sub> =(I <sub>AVE</sub> -I <sub>SET</sub> )/I <sub>SET</sub> X100%    | I <sub>OUTX</sub> =15mA, V <sub>OUTX</sub> =1V, PWM=100%                                 | -7% |      | 7%   |      |
| I <sub>MATCH</sub>                      | Channel to channel current error, I <sub>ERR_CC</sub> =(I <sub>OUTX</sub> -I <sub>AVE</sub> )/I <sub>AVE</sub> X100% | I <sub>OUTX</sub> =15mA, V <sub>OUTX</sub> =1V, PWM=100%                                 | -7% |      | 7%   |      |
| V <sub>ISET</sub>                       | ISET voltage   |  |     | 0.7  |      | V    |
| K <sub>IREF</sub>                       | IREF ratio   |  |     | 105  |      |      |
| V <sub>Dropout</sub>                    | Voltage when LED current has dropped 5%  | I <sub>OUTX</sub> =20mA, PWM=100%  |     | 0.15 | 0.3  | V    |
| <b>LOGIC INPUTS (EN, SCL, SDA, ADx)</b> |  |  |     |      |      |      |
| V <sub>IL</sub>                         | Low level input voltage  |  |     |      | 0.4  | V    |
| V <sub>IH</sub>                         | High level input voltage   |  | 1.4 |      |      |      |
| I <sub>LOGIC</sub>                      | Input current  |  | -1  |      | 1    | μA   |
| V <sub>SDA</sub>                        | SDA output low level   | I <sub>PULLUP</sub> =5mA   |     |      | 0.4  | V    |

Note1: Guaranteed by design and by statistical analysis of device characterization data. The specification is not guaranteed by production testing.

## I<sup>2</sup>C Interface Timing Requirements

| PARAMETER           |   | MIN | TYP | MAX | UNIT |
|---------------------|---|-----|-----|-----|------|
| F <sub>SCL</sub>    | Interface Clock frequency                 | -   |     | 400 | kHz  |
| T <sub>HD:STA</sub> | (Repeat-start) Start condition hold time  | 0.6 |     | -   | μs   |
| T <sub>LOW</sub>    | Low level width of SCL                    | 1.3 |     | -   | μs   |
| T <sub>HIGH</sub>   | High level width of SCL                   | 0.6 |     | -   | μs   |
| T <sub>SU:STA</sub> | (Repeat-start) Start condition setup time | 0.6 |     | -   | μs   |
| T <sub>HD:DAT</sub> | Data hold time                            | 0   |     | -   | μs   |
| T <sub>SU:DAT</sub> | Data setup time                           | 0.1 |     | -   | μs   |
| T <sub>R</sub>      | Rising time of SDA and SCL                | -   |     | 0.3 | μs   |
| T <sub>F</sub>      | Falling time of SDA and SCL               | -   |     | 0.3 | μs   |
| T <sub>SU:STO</sub> | Stop condition setup time                 | 0.6 |     | -   | μs   |
| T <sub>BUF</sub>    | Time between start and stop condition     | 1.3 |     | -   | μs   |

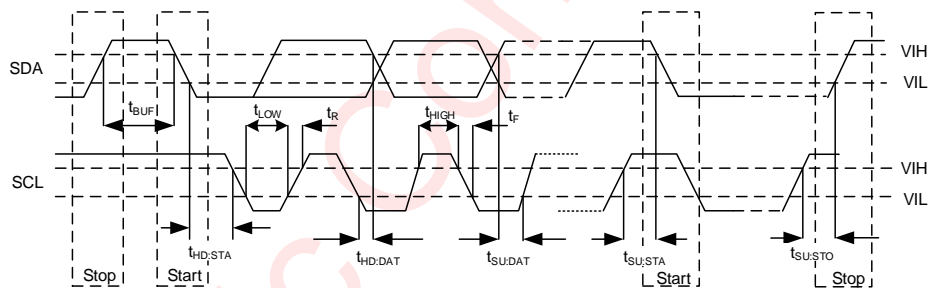


Figure 4 I2C Interface Timing

## Detailed Functional Description

### Reset

#### Power on Reset and Hardware Reset

After VDD powering on and the EN pin pulling up, I<sup>2</sup>C communication can be performed after 3ms.

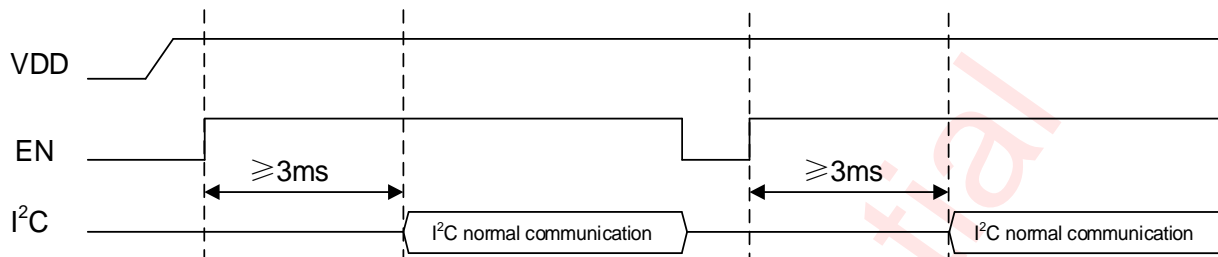


Figure 5 Power Up Timing

#### Soft Reset

Writing 0xFF into register RESET (address: 0x27), all configure registers will be reset. I<sup>2</sup>C communication can be performed after a delay of 3ms.

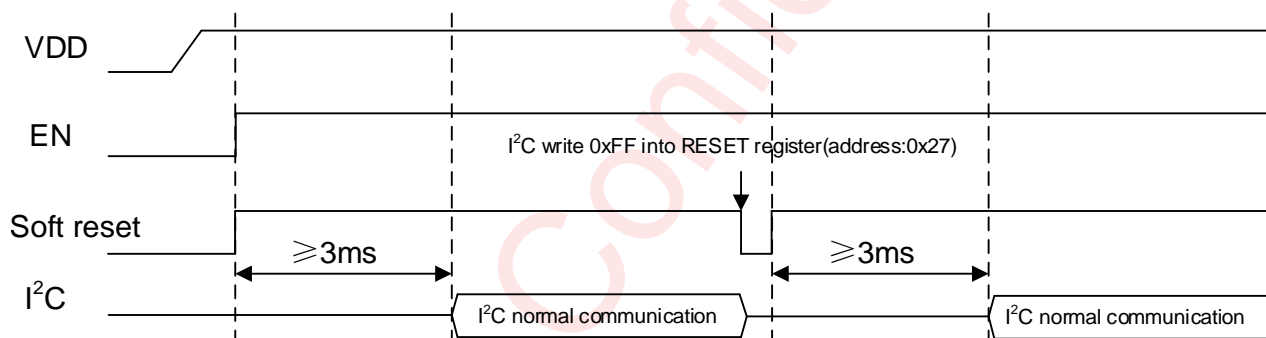


Figure 6 Software Reset Timing

## Operation Mode

#### Shutdown

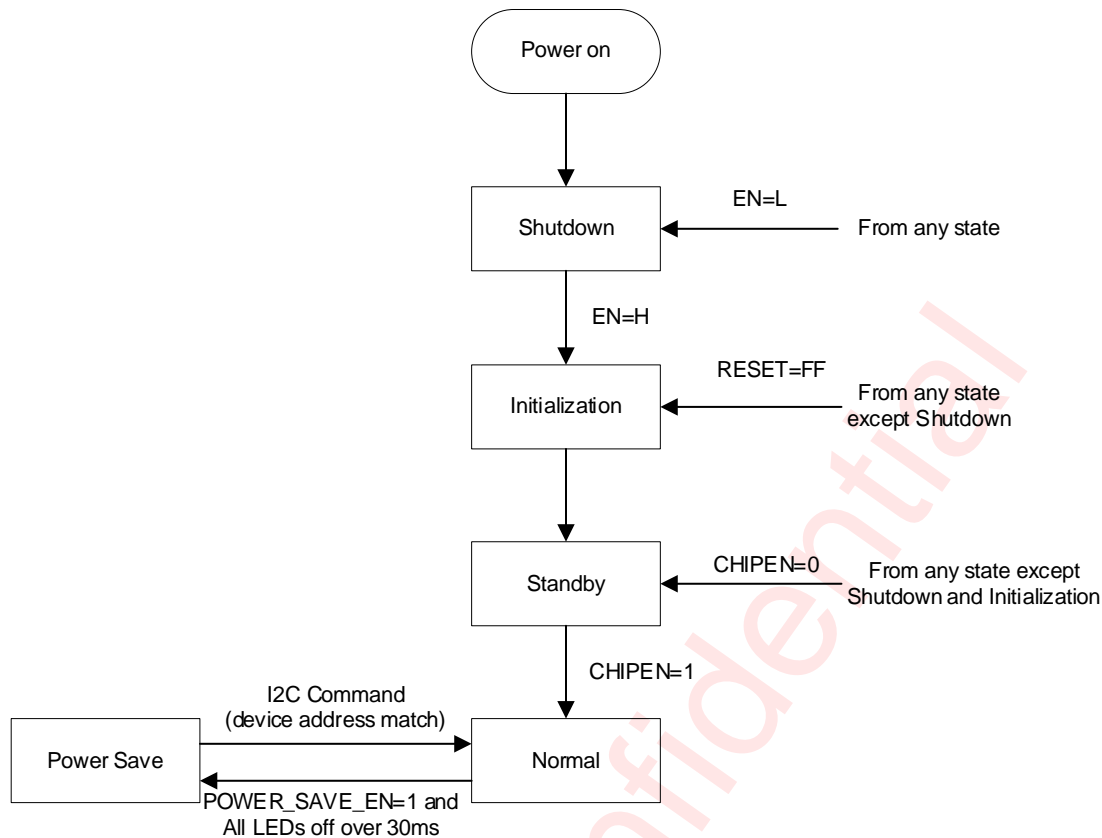
The device enters into shutdown mode automatically when EN is pulled low from any state, and all registers are reset and cannot be configured via I<sup>2</sup>C communication interface.

#### Initialization

The device enters initialization mode automatically from shutdown mode when EN is pulled high. If writing 0xFF into register RESET (address: 0x27), all configure registers will be reset, and the device will also enter initialization mode.

#### Standby

If the device completes initialization or the bit CHIPEN of register DEVICE\_CFG0 (address: 0x00.bit6) is set to "0", the device will enter standby mode. In this mode, the light control circuit is turned off, the power consumption is low, the registers data is retained, and the registers can be accessed through the I<sup>2</sup>C communication interface.



**Figure 7 Operating Mode Transition**

### **Normal**

In the following three situations, the device will enter normal mode.

- (1) In standby mode, the register CHIPEN is set to "1";
- (2) In thermal shutdown mode, the temperature reaches the recovery temperature;
- (3) In power save mode, the device is accessed with I<sup>2</sup>C device address matching.

### **Power Save**

If the bit POWER\_SAVE\_EN of register DEVICE\_CFG1 (address: 0x01.bit4) is set to "1" and all LEDs off over 30ms, the device will enter power save mode. In this mode, the light control circuit is turned off, the power consumption is low, the registers data is retained, and the registers can be accessed through the I<sup>2</sup>C communication interface.

### **PWM Control**

The device supports independent color mixing control, providing smooth and rich lighting effects.

The frequency of the output PWM signal is about 29kHz, which is greater than the audible range and can eliminate audible noise.

### **Independent Color Mixing**

Each OUT channel has an independent 8-bit color mixing register OUT3n/3n+1/3n+2\_COL (RGB, n=0~7, address: 0x0F~0x26). Each RGB LED can achieve 256 x 256 x 256 mixed color effects.

## Maximum Current Setting

The maximum output current of OUTx is set by external resistor  $R_{EXT}$  and can be expressed by the following formula:

$$I_{MAX} = K \times \frac{V_{ISET}}{R_{EXT}}$$

Where  $V_{ISET}=0.7V$ ,  $K=105$ ;

If ISET pin is connected to a small resistor or shorted to ground. The max current is limit by internal OCP circuit. More information about current limit please refer to section OCP.

## General I<sup>2</sup>C Operation

The device supports the I<sup>2</sup>C protocol in fast mode at 400kHz. The two communication lines are a serial data line (SDA) and a serial clock line (SCL). The pull-up resistor for the SDA and SCL can be selected from 1k to 10kΩ. Usually, 4.7kΩ is recommended for 400kHz I<sup>2</sup>C. The voltage level 1.8V , 3.3V and 5.0V is allowed for the I<sup>2</sup>C interface.

### Device Address

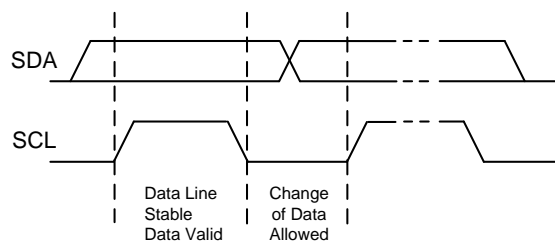
The device is defined by connecting GND or VDD to the AD0 and AD1 pins from the address. When GND or VDD is connected to the AD0 and AD1 pins, four independent device addresses can be combined (see Tables 1 ). Regardless of the settings of the AD0 and AD1 pins, the device will respond with a broadcast from the address. Perform global write operations on broadcast addresses to configure all devices simultaneously. This device supports global reading using broadcast addresses; However, the read data is only valid when all devices on the I<sup>2</sup>C bus contain the same value.

**Table 1 I<sup>2</sup>C Device Address Configuration**

| AD1 Connection | AD0 Connection | Device Address |           |
|----------------|----------------|----------------|-----------|
|                |                | Independent    | Broadcast |
| GND            | GND            | 0x28           | 0x3C      |
| GND            | VDD            | 0x29           |           |
| VDD            | GND            | 0x2A           |           |
| VDD            | VDD            | 0x2B           |           |

### Data Validation

When SCL is high level, SDA level must be stable. SDA can be changed only when SCL is low level.



**Figure 8 Data Validation Diagram**

## I<sup>2</sup>C Start/Stop

I<sup>2</sup>C start: SDA changes from high level to low level when SCL is high level.

I<sup>2</sup>C stop: SDA changes from low level to high level when SCL is high level.

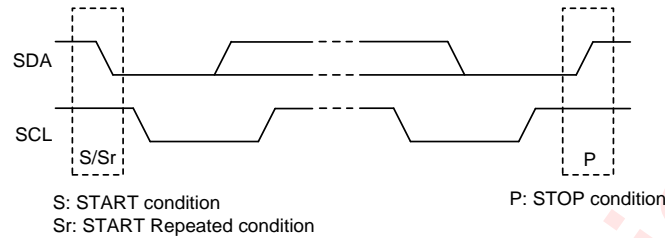


Figure 9 I<sup>2</sup>C Start/Stop Condition Timing

## Acknowledge(ACK)

ACK means the successful transfer of I<sup>2</sup>C bus data. After master sends an 8-bit data, SDA must be released; SDA is pulled to GND by slave device when slave acknowledges.

When master reads, slave device sends 8-bit data, releases the SDA and waits for ACK from master. If ACK is send and I<sup>2</sup>C stop is not send by master, slave device sends the next data. If ACK is not send by master, slave device stops to send data and waits for I<sup>2</sup>C stop.

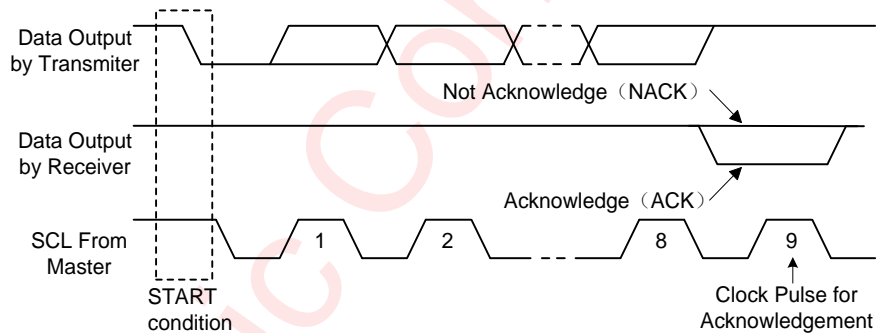


Figure 10 I<sup>2</sup>C ACK Timing

## Write Cycle

One data bit is transferred during each clock pulse. Data is sampled during the high state of the serial clock (SCL). Consequently, throughout the clock's high period, the data should remain stable. Any changes on the SDA line during the high state of the SCL and in the middle of a transaction, aborts the current transaction. New data should be sent during the low SCL state. This protocol allows a single data line to transfer both command/control information and data using the synchronous serial clock.

Each data transaction is composed of a start condition, a number of byte transfers (set by the software) and a stop condition to terminate the transaction. Every byte written to the SDA bus must be 8 bits long and is transferred with the most significant bit first. After each byte, an Acknowledge signal must follow.

In a write process, the following steps should be followed:

- Master device generates START condition. The "START" signal is generated by lowering the SDA signal while the SCL signal is high.
- Master device sends slave address (7-bit) and the data direction bit (R/W = 0).
- Slave device sends acknowledge signal if the slave address is correct.

- d) Master sends control register address (8-bit)
- e) Slave sends acknowledge signal
- f) Master sends data byte to be written to the addressed register
- g) Slave sends acknowledge signal
- h) If master will send further data bytes, the control register address will be incremented by one after acknowledge signal (repeat step f and g)
- i) Master generates STOP condition to indicate write cycle end

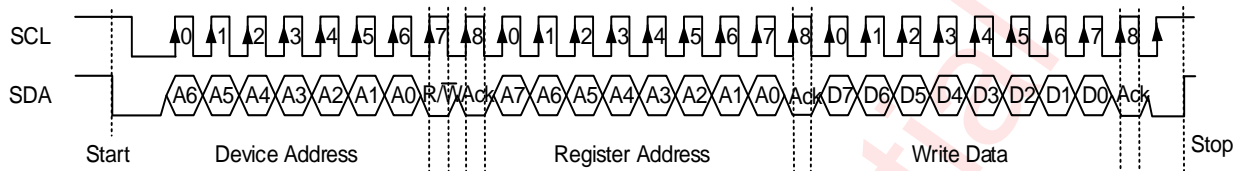


Figure 11 I2C Write Byte Cycle

### Read Cycle

In a read cycle, the following steps should be followed:

- a) Master device generates START condition
- b) Master device sends slave address (7-bit) and the data direction bit (R/W = 0).
- c) Slave device sends acknowledge signal if the slave address is correct.
- d) Master sends control register address (8-bit)
- e) Slave sends acknowledge signal
- f) Master generates STOP condition followed with START condition or REPEAT START condition
- g) Master device sends slave address (7-bit) and the data direction bit (R/W = 1).
- h) Slave device sends acknowledge signal if the slave address is correct.
- i) Slave sends data byte from addressed register.
- j) If the master device sends acknowledge signal, the slave device will increase the control register address by one, then send the next data from the new addressed register.
- k) If the master device generates STOP condition, the read cycle is ended.

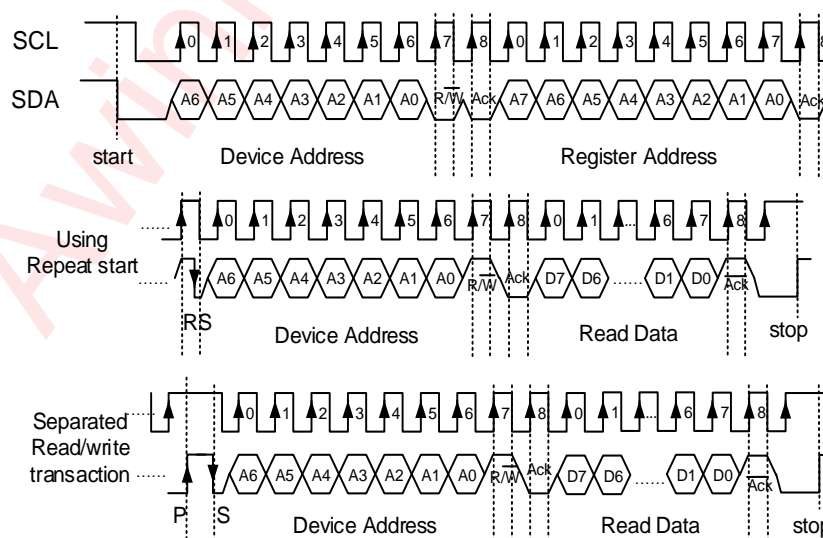


Figure 12 I2C Read Byte Cycle

## Over Current Protection (OCP)

The device monitors the current of ISET pin. When the current above the threshold, the surplus portion cannot be mirrored to the output pin, thereby limiting the maximum current.. Please refer to the electrical parameter table for specific parameters.

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**REGISTER CONFIGURATION****REGISTER LIST**

| ADDR          | NAME                            | R/W | Bit7                | Bit6   | Bit5 | Bit4          | Bit3 | Bit2 | Bit1 | Bit0           | Default |
|---------------|---------------------------------|-----|---------------------|--------|------|---------------|------|------|------|----------------|---------|
| 0x00          | DEVICE_CFG0                     | RW  |                     | CHIPEN |      |               |      |      |      |                | 0x00    |
| 0x01          | DEVICE_CFG1                     | RW  |                     |        |      | POWER_SAVE_EN |      |      |      | LED_GLOBAL_OFF | 0x3C    |
| 0x0F~<br>0x20 | OUT0_COL_CFG ~<br>OUT17_COL_CFG | RW  | OUT0_COL~ OUT17_COL |        |      |               |      |      |      |                | 0x00    |
| 0x27          | RESET                           | WO  | SOFT_RESET          |        |      |               |      |      |      |                | 0x00    |
| 0x6E          | CHIP_ID                         | RO  | CHIPID              |        |      |               |      |      |      |                | 0x41    |

## REGISTER DETAILED DESCRIPTION

| DEVICE_CFG0: (Address 00h) |          |     |  |         |
|----------------------------|----------|-----|--|---------|
| Bit                        | Symbol   | R/W | Description                              | Default |
| 7                          | Reserved | RO  | Not used                                 | 0x0     |
| 6                          | CHIPEN   | RW  | Chip enable<br>0 : Disable<br>1 : Enable | 0x0     |
| 5:0                        | Reserved | RO  | Not used                                 | 0x0     |

| DEVICE_CFG1: (Address 01h) |                |     |   |         |
|----------------------------|----------------|-----|---|---------|
| Bit                        | Symbol         | R/W | Description   | Default |
| 7:5                        | Reserved       | RO  | Not used  | 0x1     |
| 4                          | POWER_SAVE_EN  | RW  | Power save mode enable<br>0 : Disable<br>1 : Enable | 0x1     |
| 3:1                        | Reserved       | RO  | Not used  | 0x6     |
| 0                          | LED_GLOBAL_OFF | RW  | All LEDs off enable<br>0 : Disable<br>1 : Enable    | 0x0     |

| OUT0_COL_CFG~OUT17_COL_CFG: (Address 0Fh~20h) |                        |     |  |         |
|---|------------------------|-----|--|---------|
| Bit   | Symbol                 | R/W | Description  | Default |
| 7:0   | OUT0_COL~<br>OUT17_COL | RW  | OUT3n、OUT3n+1、OUT3n+2 color mixing setting when LEDn bank mode disable (n=0~5)<br>00h : The color mixing rate is 0%<br>...<br>80h : The color mixing rate is 50%<br>...<br>FFh : The color mixing rate is 100% | 0x0     |

| RESET: (Address 27h) |            |     |  |         |
|----------------------|------------|-----|--|---------|
| Bit                  | Symbol     | R/W | Description  | Default |
| 7:0                  | SOFT_RESET | WO  | Soft reset, reset all register when FFh is written | 0x0     |

| CHIP_ID: (Address 6Eh) |        |     |                                |         |
|------------------------|--------|-----|--------------------------------|---------|
| Bit                    | Symbol | R/W | Description                    | Default |
| 7:0                    | CHIPID | RO  | The CHIPID number. AW21018CQNR | 0x41    |

## Application Information

### R<sub>EXT</sub>

The maximum output current of OUTx is set by external resistor R<sub>EXT</sub> and can be expressed by the following formula:

$$I_{MAX} = K \times \frac{V_{ISET}}{R_{EXT}}$$

Where V<sub>ISET</sub>=0.7V, K=105;

To set the LED current to 15mA, R<sub>EXT</sub> should be set to 4.9kΩ.

### R<sub>R</sub>, R<sub>G</sub>, R<sub>B</sub>

The resistance(R<sub>x</sub>) used for thermal reduction can be calculated according to the following formula:

$$R_x = \frac{V_{LED} - V_{F_x} - V_{DROPOUT}}{I_{MAX}}$$

V<sub>LED</sub>: LED power supply voltage.

V<sub>F<sub>x</sub></sub>: LED forward voltage.

V<sub>DROPOUT</sub>: Voltage on LEDx, recommended values is 0.5V.

I<sub>MAX</sub>: Maximum output current.

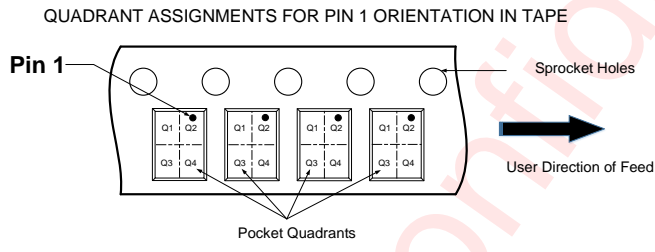
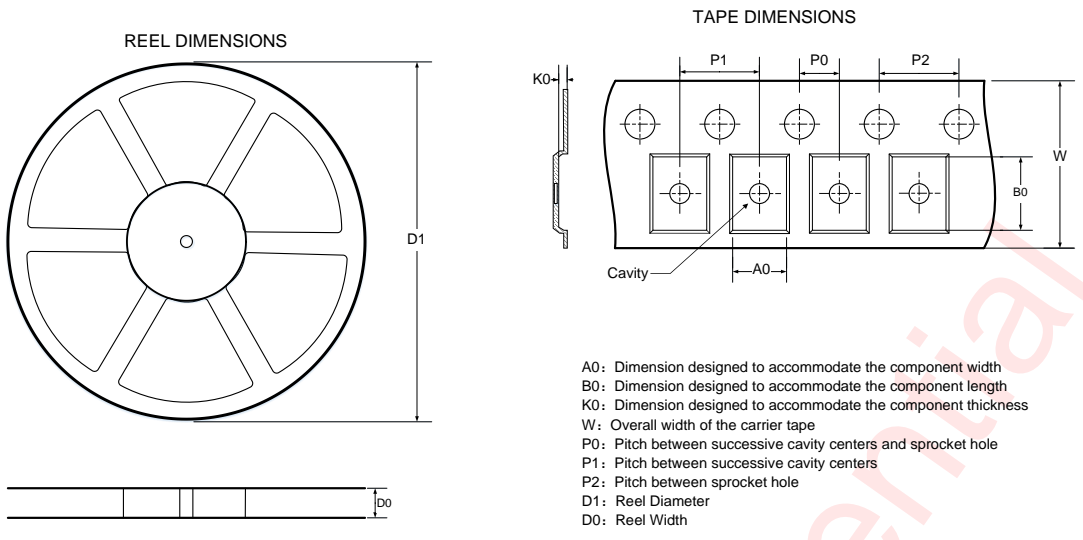
## PCB Layout Consideration

AW21018C is a 18-channel LEDs driver programmed via I<sup>2</sup>C compatible interface. When all LEDs are operating, the device power dissipation is large. To obtain the good thermal performance and avoid thermal shutdown, PCB layout should be considered carefully. Here are some guidelines:

1. The C<sub>1</sub>, C<sub>2</sub>, C<sub>LED</sub> should be placed as close to the chip as possible.
2. The C<sub>LDO</sub> should be placed as close to the PIN 32 as possible.
3. The R<sub>EXT</sub> should be placed as close to the PIN 31 as possible.
4. The Thermal PAD must be well connecting to the GND of the PCB, and add as many thermal vias as possible beneath the thermal PAD on the PCB for the heat conductivity of the device and PCB.

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### Tape And Reel Information

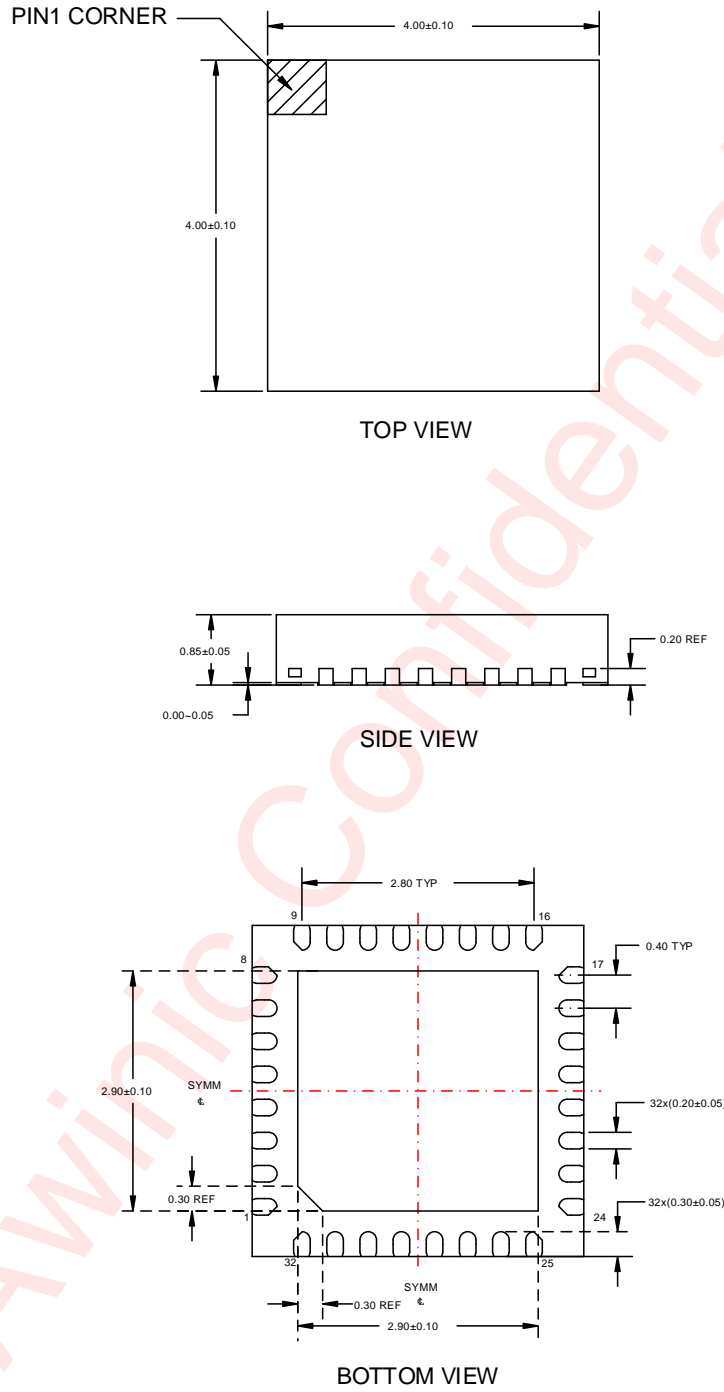


DIMENSIONS AND PIN1 ORIENTATION

| D1 (mm) | D0 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P0 (mm) | P1 (mm) | P2 (mm) | W (mm) | Pin1 Quadrant |
|---------|---------|---------|---------|---------|---------|---------|---------|--------|---------------|
| 330     | 12.4    | 4.3     | 4.3     | 1.1     | 2       | 8       | 4       | 12     | Q2            |

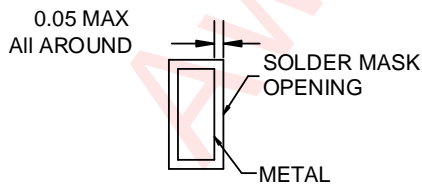
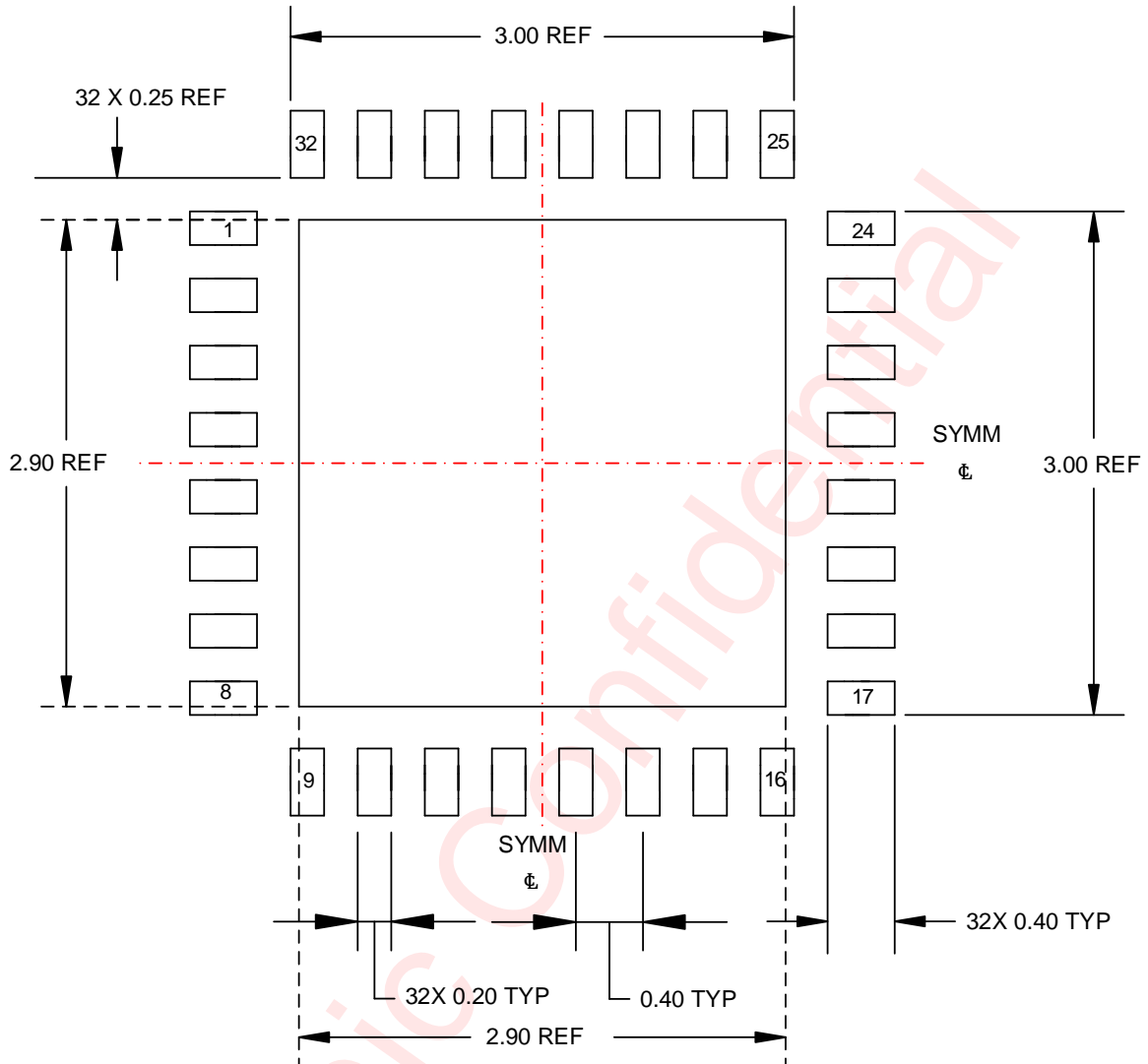
All dimensions are nominal

Package Description

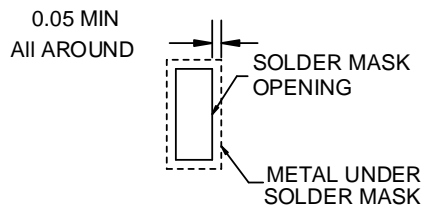


Unit: mm

Land Pattern Data



NON SOLDER MASK DEFINED



SOLDER MASK DEFINED

Unit: mm

## Revision History

| Version | Date      | Change Record       |
|---------|-----------|---------------------|
| V1.0    | Nov. 2025 | Officially released |

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